

MA2SD31

Silicon epitaxial planar type

For super high speed switching

■ Features

- $I_{F(AV)} = 200$ mA rectification is possible.
- Low forward voltage: $V_F < 0.47$ V (at $I_F = 200$ mA)

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	30	V
Repetitive peak reverse voltage	V_{RRM}	30	V
Forward current (Average)	$I_{F(AV)}$	200	mA
Peak forward current	I_{FM}	300	mA
Non-repetitive peak forward surge current *	I_{FSM}	1	A
Junction temperature	T_j	125	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$

Note) *: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

■ Package

- Code
SSMini2-F1
- Pin Name
1: Anode
2: Cathode

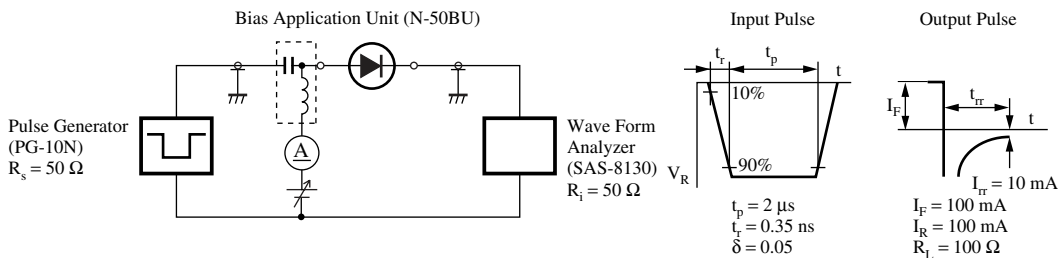
■ Marking Symbol: 8F

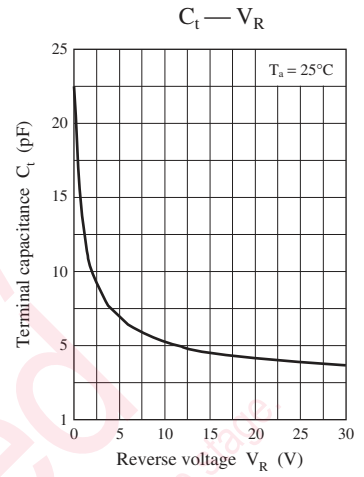
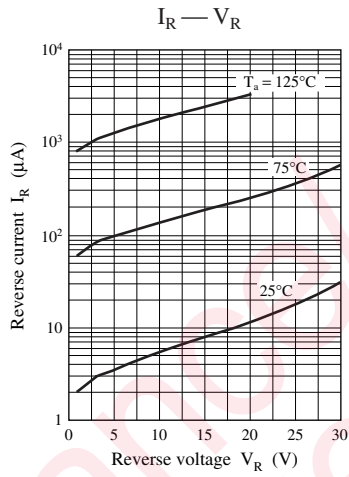
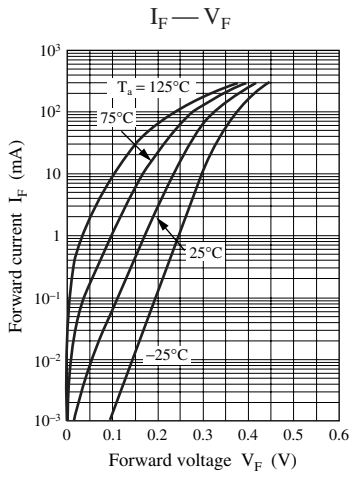
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse current	I_{R1}	$V_R = 10$ V			20	μA
	I_{R2}	$V_R = 30$ V			200	
Forward voltage	V_F	$I_F = 200$ mA		0.38	0.47	V
Terminal capacitance	C_t	$V_R = 0$ V, $f = 1$ MHz		25		pF
Reverse recovery time *	t_{rr}	$I_F = I_R = 100$ mA $I_{rr} = 10$ mA, $R_L = 100 \Omega$		2		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

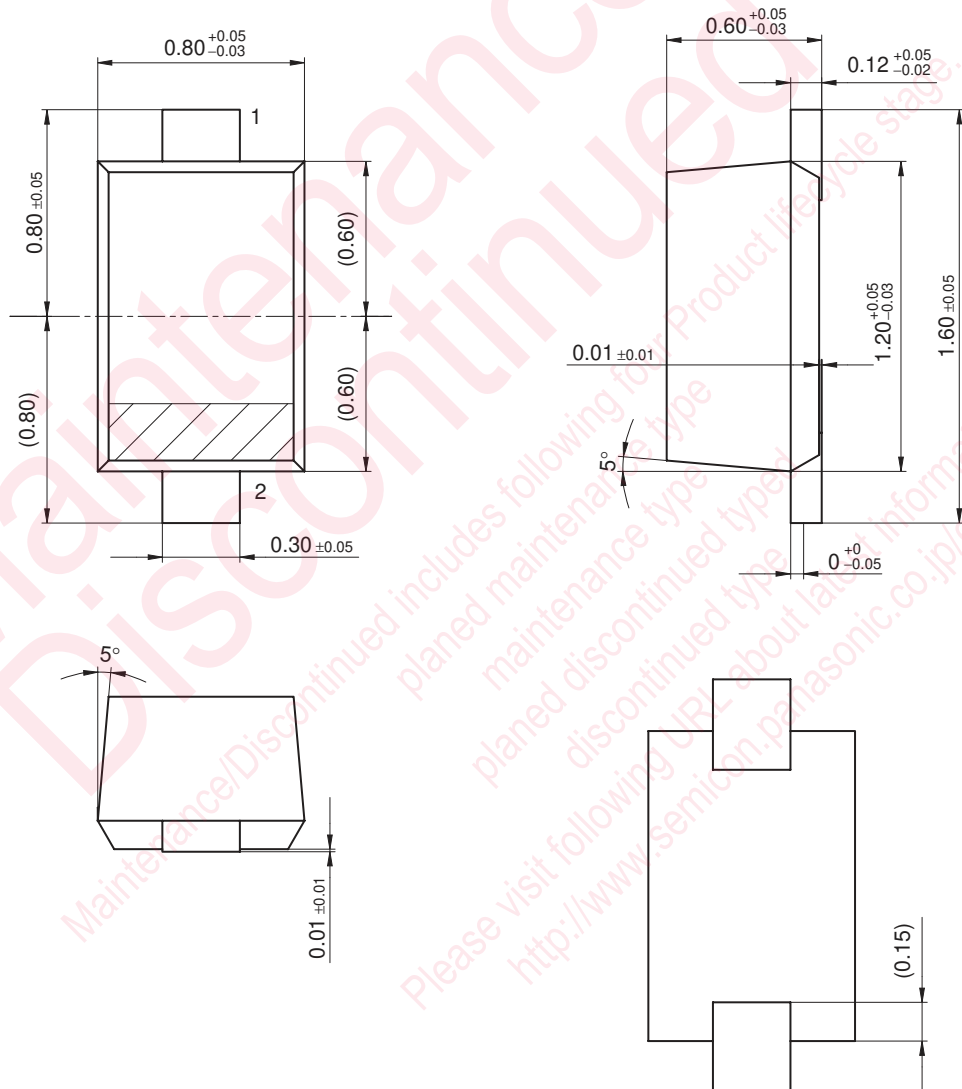
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. Absolute frequency of input and output is 250 MHz
4. *: t_{rr} measurement circuit





SSMini2-F1

Unit: mm



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